

IN THE SPECIFICATION

Page 1, before the first line, insert, -This Application is a continuation of application

serial no. 08/497,382, filed June 29, 1995.

*Now US Patent pending*

Page 3, line 16, kindly delete "or water".

IN THE CLAIMS

Kindly cancel claims 1-16.

Kindly add the following new claims:

17. A polisher having the ability to measure the thickness of a top layer of a wafer, the polisher comprising:

a polishing unit which polishes said top layer in the presence of a liquid;

an optical measurement station, mounted within said polisher but apart from

said polishing unit; and

means to move said wafer from said polishing unit to said optical measurement station while said wafer is still wet;

wherein said optical measurement station comprises;

a liquid holding unit having a window in a bottom surface thereof and holding liquid therein which receives said wafer; and

an optical thickness measuring unit located on a non-liquid side of said window which measures the thickness of said top layer while said wafer is immersed in said liquid.

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